PIN GRID ARRAY SOCKETS (PGA)

SERIES 510

STANDARD OFF THE SHELF

- S10 = HIGH TEMP NYLON 46, 150°C
SUITABLE FOR INFRARED SOLDERING
OTHER MATERIALS AVAILABLE

SERIES 540

INSULATOR WITH STANDOFFS
FOR SOLDER FILLET TOP AND BOTTOM OF PCB

- S10 = HIGH TEMP NYLON 46, 150°C
SUITABLE FOR INFRARED SOLDERING
OTHER MATERIALS AVAILABLE

SERIES 550

PULL-OFF CARRIER SOCKET
DISCARDABLE INSULATOR WITH STANDOFFS
FOR SOLDER FILLET TOP AND BOTTOM OF PCB

- S10 = HIGH TEMP NYLON 46, 150°C
SUITABLE FOR INFRARED SOLDERING
(DISCARD PLASTIC WAFER AFTER SOLDERING)
OTHER MATERIALS AVAILABLE

SERIES 575

MATERIAL FOR CUSTOM DESIGN

- N10 = .062[1.57] THICK GLASS EPOXY, FR4 140°C
- L10 = .050[1.27] THICK GLASS EPOXY, FR4 140°C
- H10 = .062[1.57] THICK POLYIMIDE HI-TEMP, 240°C

ORDERING INFORMATION

5XX-XX-XX-XXX-XXX-PXX-S10
575-XX-XX-XXX-XXX-PXX-XXX

SERIES GRID FOOTPRINT NUMBER OF PINS
MATERIAL PLATING TERMINAL ASSEMBLY
SEE TERMINAL STYLES

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